



DATE: June 8, 2022

PCN #: 2585

PCN Title: Qualified Additional Assembly/Test (A/T) Sites, Wafer Fab Backend IMD Material and Process, and Package Outline Dimension Change

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2585 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
June 8, 2022	September 8, 2022	Analog Semiconductors	A/T Sites, Wafer Fab Backend IMD Material and POD Change	2585
TITLE				
Qualified Additional Assembly/Test (A/T) Sites, Wafer Fab IMD Backend, and Package Outline Dimension Change				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified the following additional Assembly and Test (A/T) sites for select products: Diodes internal assembly and test site (SAT) located in Shanghai, China, and Shanghai SIMAT Microelectronics Technology (SIMAT) located in Shanghai, China, and Greatek located in Toufen, Taiwan.</p> <p>Diodes has also qualified high-density plasma (HDP) oxide chemical vapor deposition (CVD) as new intermetallic dielectric (IMD) material and process for select products. Some products will also be subject to a change of a respective package outline dimension (POD), in particular package height.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p>				
IMPACT				
Continuity of Supply. There will be no change to the Form, Fit or Function of products affected, unless specifically indicated in Table A below.				
PRODUCTS AFFECTED				
Table 1 - Qualified Addition A/T Site (SAT) Table 2 - Qualified Additional Wafer Fab IMD Backend Material and Process and Additional A/T Site (GTK) Table 3 - Qualified Additional A/T Site (SIMAT) Table 4 – POD Change from 2.5+-0.1mm to 2.4+-0.1mm (See Table A) Table 5 -Qualified Additional A/T Site (GTK) Table 6 - Qualified Additional Wafer Fab Backend IMD Material and Process				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notice/diodes-product-change-notice/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				



Table 1 - Qualified Additional A/T Site (SAT)

AL8843SP-13	AL8860MP-13	AL8861MP-13			
-------------	-------------	-------------	--	--	--

Table 2 - Qualified Additional Wafer Fab IMD Backend Material and Process and Additional A/T Site (GTK)

PI4IOE5V6416ZDEX	PI4IOE5V9535ZDEX	PI4IOE5V9539ZDEX	PI4IOE5V9554ZHEX	PI4IOE5V9555ZDEX	PI4IOE5V9673ZDEX
PI5USB2546HZHEX	PI6CFGL201BZDIEX				

Table 3 - Qualified Additional A/T Site (SIMAT)

AS7805ASTR-G1	AS7805AT-E1	AS7805AT-G1	AS7806AT-E1	AS7808AT-E1	AS7809AT-E1
AS7812AT-E1	AS7812AT-E1-11	AS7812AT-G1	AS7815AT-E1	AS7815AT-G1	

Table 4 - POD Change from 2.5+-0.1mm to 2.4+-0.1mm (See Table A)

G43270003	G43270009	G43270010	G43270013	G43270015	G43270016
G43270017	G43270018	G43270019	G43270021	G43270022	G43270024
G43270025	G43270027	G43270028			

Table 5 - Qualified Additional A/T Site (GTK)

PI1EQX7502AZDEX	PI3EQX7502MZDE+CWX	PI6C5946004ZHIEX	PI6CB33202ZDIEX	PI6CG18200ZDIEX-13R	PI6CG33601CZLAIEX-13R
PI2EQX502TZHEX	PI3EQX7502MZDEX	PI6C5956005ZDIEX	PI6CB33202ZDIEX-13R	PI6CG18201ZDIEX	PI6CG33602CZLAIEX
PI3A27518ZDEX	PI4MSD5V9548AZDEX	PI6CB18200ZDIEX	PI6CB33601ZLAIEX	PI6CG18201ZDIEX-01	PI6CG33602CZLAIEX-13R
PI3DBS3224ZNAEX	PI6C557-01BZHIEX	PI6CB18200ZDIEX-01	PI6CB33601ZLAIEX-13R	PI6CG18201ZDIEX-13R	PI7C9X1170CZDEX
PI3EQX501BZAEX	PI6C5913004-01ZHIEX	PI6CB18200ZDIEX-13R	PI6CB33602ZLAIEX	PI6CG33201CZDIEX	PI7C9X760CZDEX
PI3EQX501ZAEX	PI6C5913004ZHIEX	PI6CB18601ZLAIEX	PI6CB33602ZLAIEX-13R	PI6CG33201CZDIEX-13R	
PI3EQX502IZHEX	PI6C5916004ZHIEX	PI6CB18601ZLAIEX-13R	PI6CBF18501ZLAIEX	PI6CG33202CZDIEX	
PI3EQX7502AIZDEX	PI6C5922504ZHIEX	PI6CB33201ZDIEX	PI6CBF18501ZLAIEX-13R	PI6CG33202CZDIEX-13R	
PI3EQX7502BZDEX	PI6C5946002ZHIEX	PI6CB33201ZDIEX-13R	PI6CG18200ZDIEX	PI6CG33601CZLAIEX	

Table 6 - Qualified Additional Wafer Fab Backend IMD Material and Process

PI3A114-AZLEX	PI3B3253QEX	PI3USB31ZUAEX	PI49FCT3807BQE	PI5A100QEX	PI6C49X0204CWIE
PI3A223ZMEX	PI3B3253QEX-2017	PI3USB32212ZLEX	PI49FCT3807BQEX	PI5A100WEX	PI6C49X0204CWIEEX
PI3A268CZMEX	PI3B3253ZHDEX	PI3USB42ZMEX	PI49FCT3807DHEX	PI5A392AQEX	PI6C49X0206TLIE
PI3A288ZMEX	PI3B3257LE	PI3USB9281CGEEX	PI49FCT3807DQE	PI5L200LEX	PI6C49X0206TLIEEX
PI3A3899ZTAEX	PI3B3257LEX	PI3USB9281CXWEX	PI49FCT3807DQEX	PI5L200WEX	PI6C49X0208ZHIEEX
PI3A412ZHEX	PI3B3257QE	PI3V713-AZLEX	PI4IOE5V6408ZTAEX	PI5USB2544ZHEX	PI6C49X0210-AZHIEX
PI3A6386ZLEX	PI3B3257QEX	PI49FCT20802QE	PI4IOE5V6408ZTAEX-13	PI5USB2546AZHEX	PI6C49X0210ZHIEEX
PI3B3125LE	PI3B3257WE	PI49FCT20802QEX	PI4IOE5V6416LEX	PI5USB2546HZHDEX	PI6CDBL401BZHIEEX
PI3B3125LEX	PI3B3257WEX	PI49FCT32802LE	PI4IOE5V9535LEX	PI5USB2546JZHEX	PI6CDBL402BLIE
PI3B3125QE	PI3B3257ZHDEX	PI49FCT32802LEX	PI4IOE5V9536UEX	PI5USB2546ZHDEX	PI6CDBL402BLIEEX
PI3B3125QEX	PI3B3861QE	PI49FCT32802QE	PI4IOE5V9537UEX	PI5USB2546ZHEX	PI6CFGL202BLIEEX
PI3B3125WE	PI3B3861QEX	PI49FCT32802QEX	PI4IOE5V9538LE	PI5USB30216CXUAEX	PI6CFGL401BZHIEEX
PI3B3125WEX	PI3CSW12ZUAEX	PI49FCT32803LEX	PI4IOE5V9538LEX	PI5USB30216DXUAEX	PI6CFGL402BLIEEX
PI3B3126LE	PI3L100QE	PI49FCT32803QE	PI4IOE5V9539LE	PI6C10806BLEX	PI6CFGL601BZHIEEX
PI3B3126LEX	PI3L100QEX	PI49FCT32803QEX	PI4IOE5V9539LEX	PI6C49CB01JWEX	PI6CV2304LE
PI3B3126QE	PI3USB102JXUCEX	PI49FCT32805QE	PI4IOE5V9554ALEX	PI6C49CB02JWEX	PI6CV2304LEX
PI3B3126QEX	PI3USB102ZLEX	PI49FCT32805QEX	PI4IOE5V9554LE	PI6C49CB04AJWEX	PI6CV2304WE
PI3B3245LEX	PI3USB102ZMEX	PI49FCT32807QE	PI4IOE5V9554LEX	PI6C49CB04BJWEX	PI6CV2304WEX
PI3B3245QE	PI3USB103ZLEX	PI49FCT32807QEX	PI4IOE5V9555LE	PI6C49CB04CJWEX	PI6CV304LEX
PI3B3245QEX	PI3USB14-ALE	PI49FCT3805CHE	PI4IOE5V9555LEX	PI6C49X0201WIE	PI6CV304WE
PI3B3245QEX-2017	PI3USB14-ALEX	PI49FCT3805DHEX	PI4IOE5V9557LEX	PI6C49X0201WIEEX	PI6CV304WEX
PI3B3251LE	PI3USB14-AZHE	PI49FCT3805DQE	PI4IOE5V96224ZLEX	PI6C49X0202WIE	PSMUX154ZMEX
PI3B3251LEX	PI3USB14-AZHEX	PI49FCT3805DQEX	PI4IOE5V96248ZLEX	PI6C49X0202WIEEX	PT7C4337ACSE
PI3B3251QE	PI3USB221AZUAEX	PI49FCT3805QE	PI4ULS3V204GAEX	PI6C49X0204AWIE	PT7C4337ACSEEX
PI3B3251QEX	PI3USB221AZWEX	PI49FCT3805QEX	PI4ULS3V204LE	PI6C49X0204AWIEEX	PT7C4337AWEX
PI3B3253LE	PI3USB221EZUAEX	PI49FCT38072BHEX	PI4ULS3V204LEX	PI6C49X0204B-AWE	PT7C4337UEX
PI3B3253LEX	PI3USB221EZWEX	PI49FCT38072CQE	PI4ULS3V204ZBEX	PI6C49X0204B-AWEX	
PI3B3253QE	PI3USB30EZMEX	PI49FCT38072CQEX	PI5A100QE	PI6C49X0204BWIEX	

Table A

	Current	New
Total Package Height	2.5±0.1mm	2.4±0.1mm

Current G4 TYPE height spec

New G4 TYPE height spec

OUTLINE DIMENSIONS

OUTLINE DIMENSIONS

